

ABSTRACT OF THE INVENTION

A method is disclosed for preparing an electronic assembly using a reworkable
5 underfill encapsulant in which the underfill encapsulant is cured in situ from a curable
composition comprising one or more mono-functional maleimide compounds, or one or
more mono-functional vinyl compounds other than maleimide compounds, or a
combination of maleimide and vinyl compounds, a curing initiator and optionally, one or
more fillers or adhesion promoters.

This Sheet Has Been Replaced

